PCN Number: PCN#202		[‡] 20250	0124000.1			PCN Date:		Ja	anuary 24, 202	25		
Title	Qualification	n of add	litional	Ass	embly sites for	select TS	SSC	OP de	evices			
Cust	omer Contact:		Chang	ge N	Management Team Dept:			Quali	ty Services			
Proposed 1 st Ship Date: April 2			24,	2025	Sample requests accepted until:			Marcl	h 25, 2025*			
*Sai	mple requests	receive	d after	Ma	rch 25, 2025	will not	be	sup	porte	d.		
Cha	nge Type:											
\boxtimes	Assembly Site				Design	Wafer Bump Materia			mp Material			
	Assembly Proce	ess			Data Sheet Wafer Bump Proc		mp Process					
Assembly Materials				Part number change Wafer Fab Site		Site						
Mechanical Specification				Test Site		Wafe	Wafer Fab Material					
Packing/Shipping/Labeling				Test Process				Wafe	er Fab	Process		
	DON D. L. Y.											

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:

TSSOP (PW) Build sites					
Assembly Sites	TAI, MLA, TIEMA, CDAT, ASEHAT, CAR, TFME				
	4211471				
	4206193				
	4228573				
	4226323				
Mold Compound	4209002				
	8095178				
	SID#R-31				
	SID#EN2000507				
	SID#438518				
	4147858				
	4211470				
	4207768				
Mount Compound	4208458				
Mount Compound	4042500				
	4213245				
	434165				
	SID#EY1000063				
Leadframe Finish NIPDAU, Matte Sn					
Bond Wire (mil)	Cu (0.7,0.8, 0.96, 1.0,1.15), Au (0.96)				

Upon expiry of this PCN, TI will combine lead finish solutions in a single standard part number. For example, a customer order for 7500 units of a specific TI part number with 2500 units SPQ (Standard Pack Quantity per reel) may be fulfilled in the following ways:

- 3 reels of NiPdAu finish.
- 3 reels of Matte Sn finish
- 2 reels of Matte Sn and 1 reel of NiPdAu finish
- 2 reels of NiPdAu and 1 reel of Matte Sn finish

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

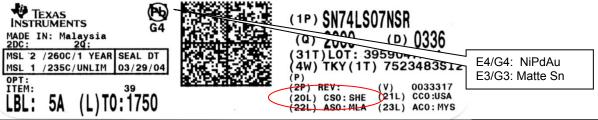
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
No Change			

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TAI	TAI	TWN	Chung Ho, New Taipei City
TFME	NFM	CHN	Economic Development Zone
CAR	CAR	MYS	Ipoh
ASESH	ASH	CHN	Shanghai
CDAT	CDA	CNN	Chengdu
TIEM	CU6	MYS	Melaka
TI Malaysia	MLA	MYS	Kuala Lumpur

Sample product shipping label (not actual product label)



Product Affected:

CD4021BPWR	SN74HCS02PWR	SN74HCS264PWR	TLV4314IPWR
CD4023BPWR	SN74HCS03PWR	SN74HCS266PWR	TLV4316IPWR
CD4024BPWR	SN74HCS04PWR	SN74HCS27PWR	TLV4379IPWR
CD4049UBPWR	SN74HCS05PWR	SN74HCS30PWR	TLV7034PWR
CD4070BPWR	SN74HCS09PWR	SN74HCS32PWR	TLV7044PWR
CD74HC173PWR	SN74HCS10PWR	SN74HCS367PWR	TLV8544PWR
CD74HC237PWR	SN74HCS11PWR	SN74HCS594PWR	TLV9024PWR
CD74HCT238PWR	SN74HCS125PWR	SN74HCS595PWR	TLV9034PWR
DRV8847SPWR	SN74HCS126PWR	SN74HCS596PWR	TLV9044IPWR
INA4180A1IPWR	SN74HCS137PWR	SN74HCS7002PWR	TLV9164IPWR
INA4180A2IPWR	SN74HCS138PWR	SN74HCS7266PWR	TLV9364IPWR
INA4180A3IPWR	SN74HCS139PWR	SN74HCS72PWR	TMUX1108PWR
LM339LVPWR	SN74HCS14PWR	SN74HCS74PWR	TMUX1109PWR
LMK1C1106PWR	SN74HCS151PWR	SN74HCS86PWR	TMUX1111PWR
PCA9554PWR	SN74HCS153PWR	SN74HCT165PWR	TMUX1308PWR
SN0402093PWR	SN74HCS164PWR	SN74HCT595PWR	TMUX1309PWR
SN74AVC4T774PWR	SN74HCS16507PWR	SN74LV367APWR	TMUX6111PWR
SN74AXCH4T245PWR	SN74HCS165PWR	SN74LV4T125PWR	TMUX6112PWR
SN74HC00APWR	SN74HCS166PWR	SN75101PWR	TRS3232ECPWR
SN74HC151PWR	SN74HCS174PWR	SN75C3232EPWR	TRSF3221ECPWR
SN74HC175PWR	SN74HCS21PWR	TL084HIPWR	TRSF3221EIPWR
SN74HC20PWR	SN74HCS237PWR	TL3474CPWR	TRSF3232ECPWR
SN74HC367PWR	SN74HCS238PWR	TL3474IPWR	TXU0304PWR
SN74HC368PWR	SN74HCS251PWR	TL3474MIPWR	
SN74HCS00PWR	SN74HCS259PWR	TLV4313IPWR	



TSSOP Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	MLA TCA6416PW	TIEMA LM5037MTNOPB
TC	Temperature Cycling -85/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/86/0 (DAC70004IPW)	3/66/0 (LDC1000PW)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TFME SN74HCS74PW	TAI TLC59116ITPWRQ1 LDC5072A0PWQ1
TC	Temperature Cycling -85/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/86/0	3/66/0 (SN0901056B1PW)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	A SE SHAT L SF0108QPWRQ1 LM2902PW	CAR BQ26501PW TP \$53125PW PGA309AIPW
TC	Temperature Cycling -85/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH	96 hours Or 264 hours	3/231/0	3/231/0

	Stress Test	Duration	A SE SHAT L SF0108QPWRQ1 LM2902PW	CAR BQ26501PW TP \$53125PW PGA309AIPW
	Or Temperature Humidity Bias,	Or 1000 hours		
HTSL	85C/85%RH High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (TL1431CPW)	3/66/0 (DRV603PW)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	CDAT MAX202IPW
TC	Temperature Cycling -85/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0 (Note 1)
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/86/0
MQ	Manufacturability	-	Pass

Note 1 - bHAST performed on CD4060BPWR (MLA), with 1 lot performed TMUX1308QPWRQ1 (CDAT) as part of enterprise qualification.

Devices LSF0108QPWRQ1, LM2902PW, SN74HCS74PW, TPS53125PW, TCA6416PW, LM5037MTNOPB, TLC59116ITPWRQ1, PGA309AIPW, MAX202IPW, CD4060BPWR qualified at MSL1 rating. Devices BQ26501PW qualified at MSL2 and device LDC5072A0PWQ1 qualified at MSL3.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable.
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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